



WCN Opto Group Co., Limited

WCN-5712GU-DC01-T

SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2016-3-28	Athena		
REVISION RECORD			



REVISION: A0

WCN Opto Group Co., Limited

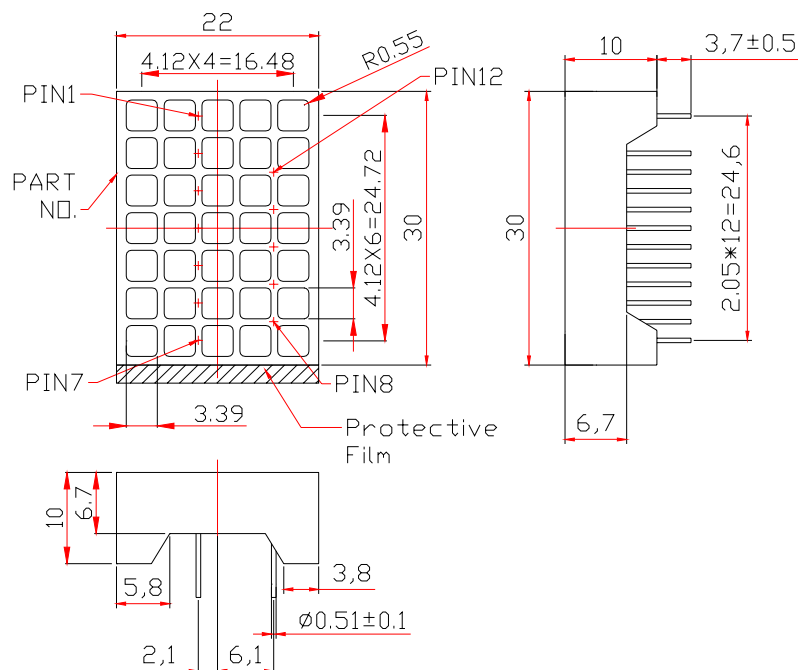
■ Features:

- **High Reliability**
- **Color: Yellow Green**
- **Low Power Requirement**
- **Flat Package and Light Weight**
- **Easy Assembly**

■ **Description:**

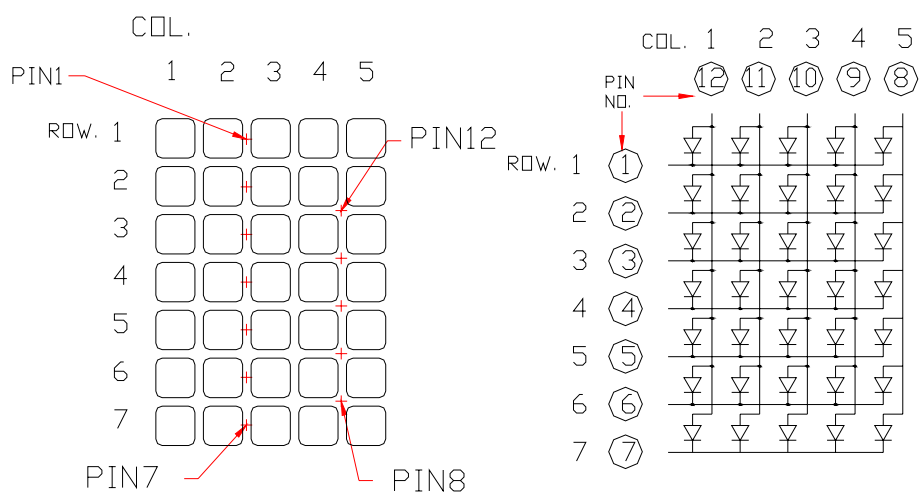
- **5*7 LED Dot Matrix**
- **3.39*3.39mm Block and Pitch 4.12 mm**
- **Black Face and Milky Dots**

Outer Dimensions



Notes : Unless otherwise stated, The tolerance is $\pm 0.25\text{mm}$.

■ Circuit Diagram



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■ Absolute Maximum Rating (Ta=25°C) / Per Dice:

Parameter	Symbol	Condition	Color	Rating	Units
Maximal Power Dissipation (When completely Lighting)	P _d	—	Yellow Green	65	mW
Maximal Forward Current (When completely Lighting)	I _F	—	Yellow Green	25	mA
Peak Forward Current	I _{FP}	1/8Duty 10khz	Yellow Green	100	mA
Reverse Voltage	V _R	—	Yellow Green	5	V
Operating Temperature Range	T _{opr}	—	—	-40~+85	°C
Storage Temperature Range	T _{stg}	—	—	-40~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Dice	1.80	2.25	2.60	V
Reverse Current	I _R	V _R =5V	Per Dice	—	—	100	μA
Luminous Intensity	I _v	I _F =10mA	Per Dice	1.751	3.5	6.1	mcd
Wave Length	λ _p	I _F =20mA	Per Dice	—	568	—	nm
	λ _d				571		
Spectral Line Half Width	△λ	I _F =20mA	Per Dice	—	20	—	nm
Luminous Intensity Matching Ratio (Dot To Dot)	I _{V-M}	1/8Duty I _{FP} =40mA				1.2:1	

■ Luminous Intensity Sorting (1/8Duty ; I_{FP} =40mA ;The Tolerance is +/-10%)

BIN Color	I	J	K	L	M
Yellow Green (mcd)	1.751-2.35	2.351-3.05	3.051-4.0	4.001-5.000	5.001-6.1

■ Soldering Conditions: Soldering Temp. ≤+260°C

Soldering Time. ≤3sec.

(at 2mm Distance from The Case of Reflector Edge)

■ Typical Elector-Optical Characteristics Curve:

Fig1. Forward Current vs. Forward Voltage:

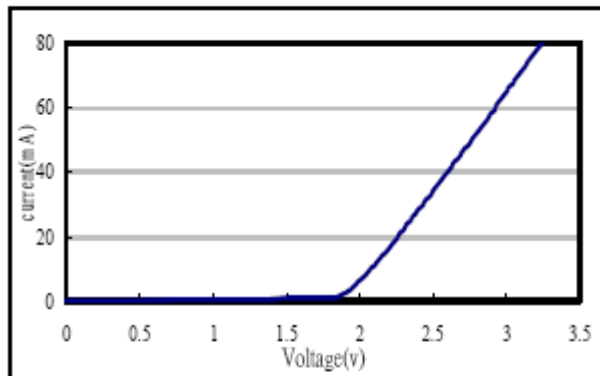


Fig2. Forward Current vs. Relative Intensity:

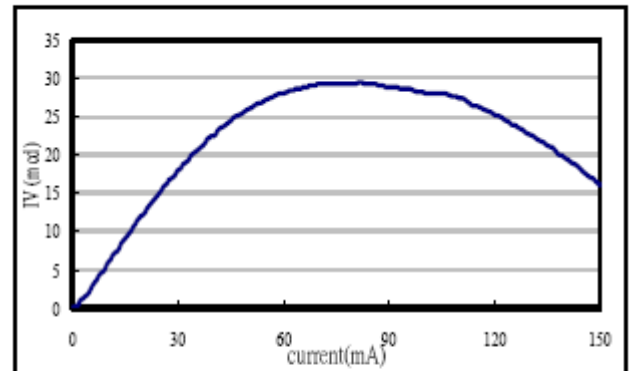


Fig3. Forward Current vs. Relative Wavelength:

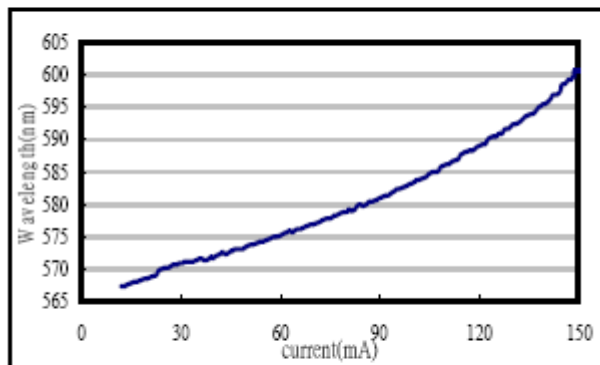


Fig4. Temperature vs. Relative Intensity:

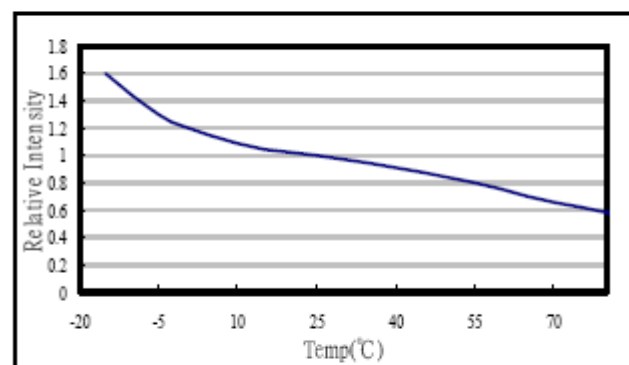


Fig5. Temperature vs. Relative Wavelength:

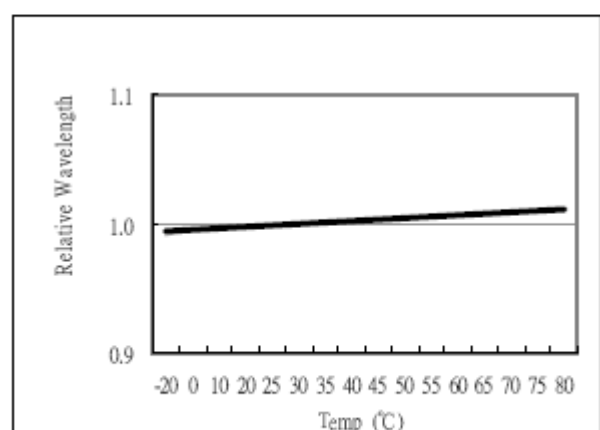
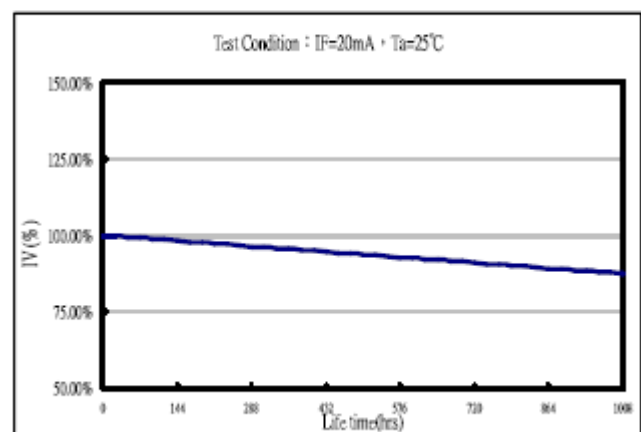


Fig6. Life Test at 20mA R.T. 1000hrs:



LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C(COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T.SOL=230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T.SOL=260±5°C DWELL TIME=10±1sec.

Packing method A:

70 pcs / Expandable Polyethylene.

350 pcs / Box(360*175*130mm).

2100 pcs / Catton(550*380*280mm).